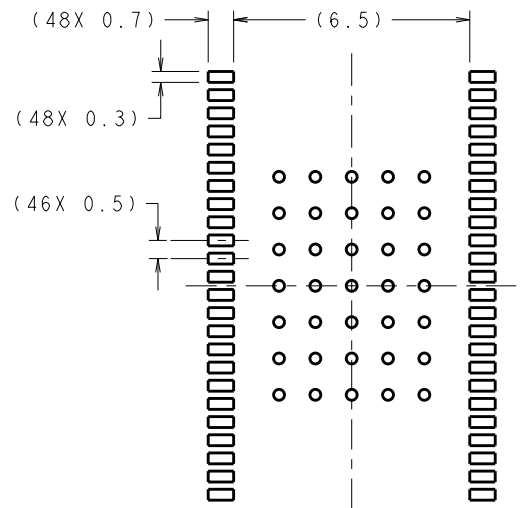
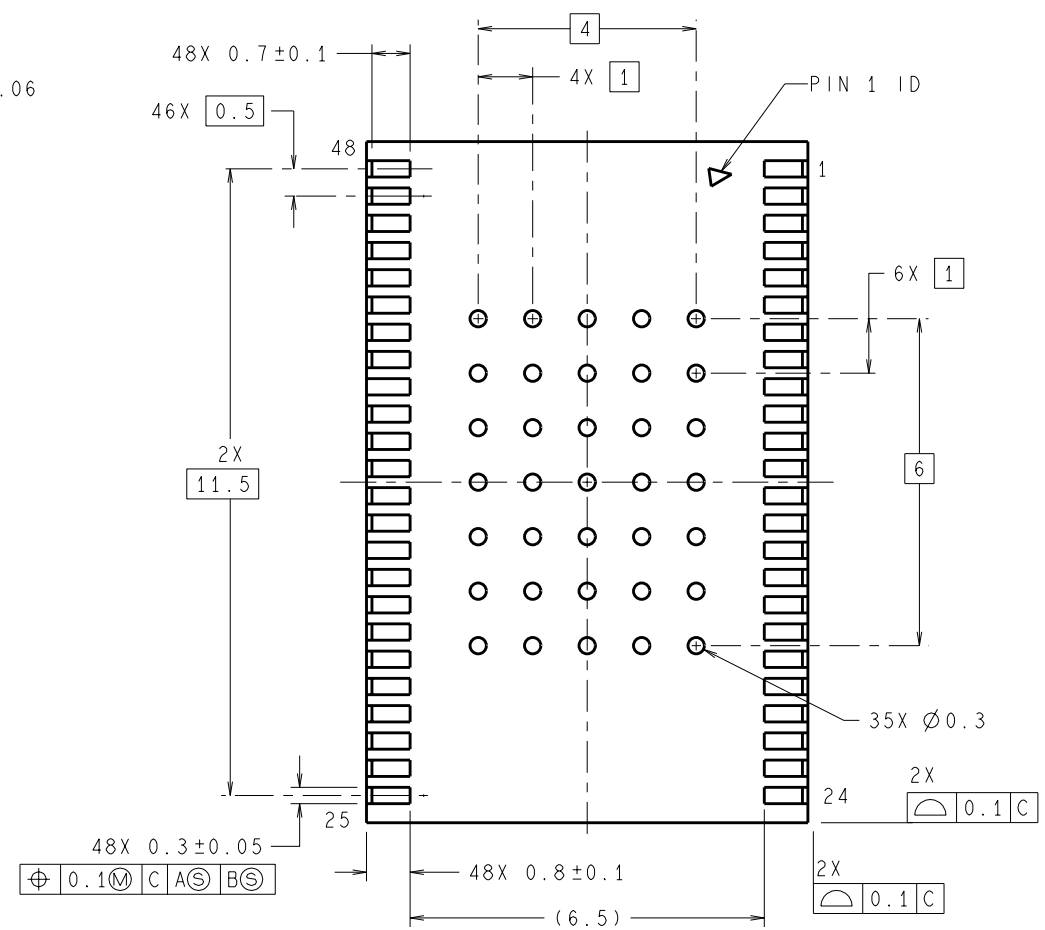
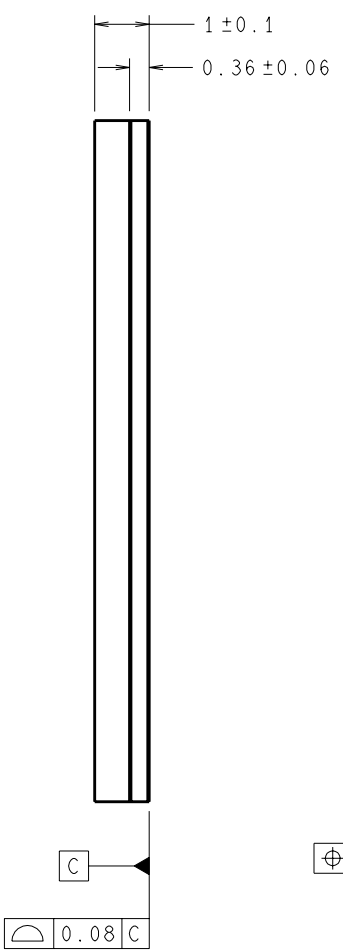
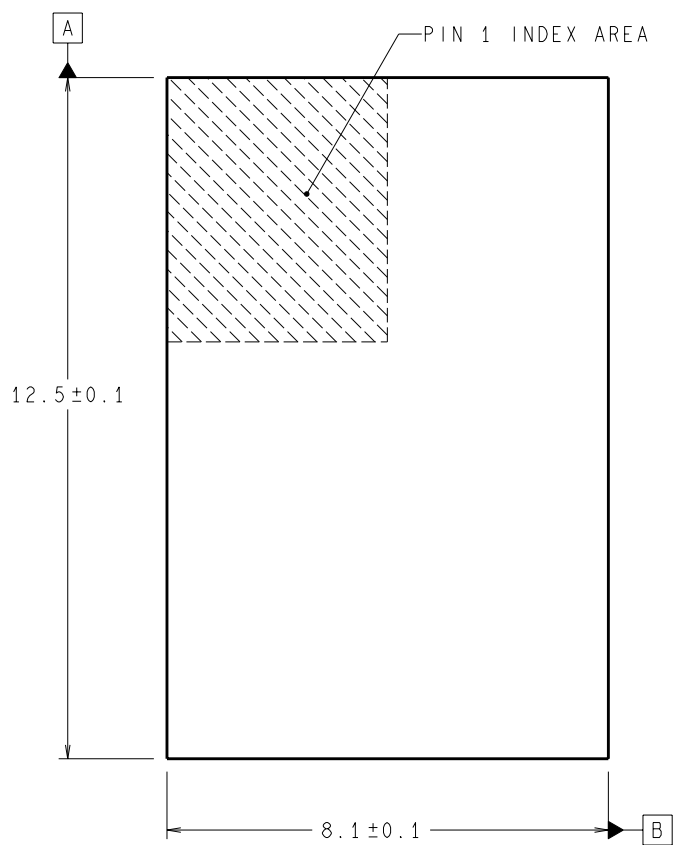


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12056	09/24/1998	TL/KH
B	ADD THERMAL PADS TO THE LAND PATTERN	12347	02/23/2000	TL/WL



DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS



- NOTES: UNLESS OTHERWISE SPECIFIED.
- MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
 - PLATING: Cu 15 TO 20 MICROMETERS
Ni 10 ± 5 MICROMETERS
Au 1 ± 0.5 MICROMETER
 - REFERENCE JEDEC MO-209, VARIATION HDBH, DATED SEPTEMBER 1998.

APPROVALS	DATE	National Semiconductor		
DRAWN T. LEQUANG	09/24/1998	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. MARTA SUCHY	02/23/2000	CSP, PLASTIC, LAMINATED, 8.1 X 12.5 X 1.0 mm BODY, 48 L, 0.5 mm PITCH		
ENGR. CHK. WAYNE LEE	02/23/2000			
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	(SC)MKT-SLB48A	B
INCH [MM]	FORMERLY: N/A	SHEET 1 of 1		